



Material Content Data Sheet



Sales Product Name		BSC196N10NS G		Issued		19. January 2018		
MA#		MA001632788						
Package		PG-TDSON-8-1		Weight*		120.78 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.247	1.86	1.86	18606	18606
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		94	
	non noble metal	iron	7439-89-6	0.038	0.03		313	
	non noble metal	copper	7440-50-8	37.762	31.26	31.30	312661	313068
	non noble metal	copper	7440-50-8	0.048	0.04	0.04	402	402
wire	non noble metal	copper	7440-50-8	0.048	0.04	0.04	402	402
encapsulation	organic material	carbon black	1333-86-4	0.084	0.07		694	
	plastics	epoxy resin	-	5.955	4.93		49303	
	inorganic material	silicondioxide	60676-86-0	35.895	29.72	34.72	297209	347206
leadfinish	non noble metal	tin	7440-31-5	1.452	1.20	1.20	12019	12019
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1371	1371
solder	non noble metal	tin	7440-31-5	0.043	0.04		360	
	noble metal	silver	7440-22-4	0.054	0.04		450	
	non noble metal	lead	7439-92-1	2.075	1.72	1.80	17180	17990
heatspreader	inorganic material	phosphorus	7723-14-0	0.003	0.00		28	
	non noble metal	iron	7439-89-6	0.011	0.01		94	
	non noble metal	copper	7440-50-8	11.320	9.37	9.38	93728	93850
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.007	0.01		55	
	non noble metal	iron	7439-89-6	0.022	0.02		185	
	noble metal	silver	7440-22-4	1.289	1.07		10677	
	non noble metal	copper	7440-50-8	22.292	18.46	19.56	184571	195488
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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